

Amendments to the Claims

The listing of claims will replace all prior versions, and listings of claims in the application.

1. (currently amended) A cleaning device for process gases that is configured to generate clean process gas from contaminated process gas in a reflow soldering system, comprising:

a cleaning chamber comprising,

a cleaning liquid configured to clean the contaminated process gas, said cleaning chamber allowing the contaminated process gas to flow therein via a supply line and allowing the cleaned process gas to flow therefrom via a discharge line; ~~and~~

a first deposition wall having a first surface, the surface being configured to receive a film of the cleaning liquid and being configured to be an outer wall of the cleaning device; and

a second deposition wall positioned centrally within the cleaning chamber and having a second surface facing the first surface, the second surface being configured to receive another film of the cleaning liquid.

2. (previously presented) The cleaning device according to claim 10, wherein the plurality of modules includes modules having different operative principles of deposition that are connected one after the other in series.

3. (previously presented) The device according to claim 2, wherein a flow path for the cleaning liquid extends through the series-connected modules in such a manner that the direction of flow of the cleaning liquid is opposite to the direction of flow of the process gas.

4. (currently amended) The cleaning device according to claim 10, ~~wherein the further comprising a plurality of~~ cleaning liquids ~~have~~ having different cleaning properties, such that respective ones of which are provided in respective ones of a the plurality of ~~the cleaning chambers corresponding to each of the~~ modules arranged in the successive order.

5. (previously presented) The cleaning device according to claim 1, wherein the cleaning chamber comprises a bath comprising the cleaning liquid, the supply line coupled below the liquid level of the bath.

6. (canceled)

7. (currently amended) The cleaning device according to claim 1, wherein there are a plurality of the first and second deposition walls that are arranged perpendicular or with a slope with respect to each other in the cleaning chamber and ~~the~~ a supply for the cleaning liquid is arranged in an area on top of edges of the plurality of first and second deposition walls.

8. (previously presented) The cleaning device according to claim 1, wherein at least one respective injection opening for the cleaning liquid is directed into the cleaning chamber.

9. (previously presented) The cleaning device according to claim 1, wherein the cleaning chamber comprises a respective outlet that is connected to a clarifying device for the cleaning liquid.

10. (previously presented) The cleaning device according to claim 1, wherein the cleaning chamber comprises a plurality of modules arranged in parallel configured to allow for a predetermined throughput and, in successive order, to allow for a predetermined degree of purity for the process gas.

11. (currently amended) A system, comprising:

a plurality of separate deposition walls each having a surface, the surface being configured to receive a film of a cleaning liquid that is configured to clean a contaminated process gas, the contaminated process gas flowing into the plurality of separate deposition walls via a supply line and from the plurality of separate deposition walls via a discharge line,

wherein a supply for the cleaning liquid is arranged in an area on top of edges of the plurality of separate deposition walls, ~~and~~

wherein at least one of the plurality of separate deposition walls is an inner surface of an outer wall of the system, and

wherein a respective one of the plurality of separate deposition walls is centrally located within the system and has first and second surfaces, the first and second surfaces each being configured to receive another film of the cleaning liquid.

12. (previously presented) The cleaning device according to claim 19, wherein the plurality of modules includes modules having different operative principles of deposition that are connected one after the other in series.

13. (previously presented) The device according to claim 12, wherein a flow path for the cleaning liquid extends through the series-connected modules in such a manner that the direction of flow of the cleaning liquid is opposite to the direction of flow of the process gas.

14. (currently amended) The cleaning device according to claim 19, ~~wherein the~~
further comprising a plurality of cleaning liquids ~~have~~ having different cleaning properties,
such that respective ones of which are provided in respective ones of each of the modules
arranged in the successive order.

15. (currently amended) The cleaning device according to claim 11, wherein the
supply ~~of~~ for the cleaning liquid comprises a bath, the supply line coupled below a liquid
level of the bath.

16. (previously presented) The cleaning device according to claim 11, wherein the
plurality of separate deposition walls are arranged perpendicular or with a slope with respect
to each other.

17. (previously presented) The cleaning device according to claim 11, wherein at
least one respective injection opening for the cleaning liquid is directed into the plurality of
separate deposition walls.

18. (previously presented) The cleaning device according to claim 11, wherein the
plurality of separate deposition walls comprises a respective outlet that is connected to a
clarifying device for the cleaning liquid.

19. (previously presented) The cleaning device according to claim 11, wherein the
plurality of separate deposition walls comprises a plurality of modules arranged in parallel

configured to allow for a predetermined throughput and, in successive order, to allow for a predetermined degree of purity for the process gas.

20. (currently amended) A cleaning device for process gases that is configured to generate clean process gas from contaminated process gas in a reflow soldering system, comprising:

a cleaning chamber configured to allow the contaminated process gas to flow therein via a supply line and the cleaned process gas to flow therefrom via a discharge line, the cleaning chamber comprising,

at least one first deposition wall having a first surface, the surface being configured to receive a film of cleaning liquid and being configured to be an outer wall of the cleaning device;

at least one second deposition wall positioned centrally within the cleaning chamber and having a second surface facing the first surface, the second surface being configured to receive another film of the cleaning liquid;

a supply for the cleaning liquid arranged internally in the cleaning chamber in an upper area of the at least one first deposition wall and the at least one second deposition wall, configured to provide the ~~film~~ films of cleaning liquid such that the ~~film~~ films of cleaning liquid ~~traps~~ trap contaminants and ~~flows~~ flow downward along the at least one first deposition wall and the at least one second deposition wall, the supply for the cleaning liquid constantly replacing the ~~film~~ films of cleaning liquid; and

an outlet configured to collect the cleaning liquid and trapped contaminants at a lower area of the cleaning chamber.